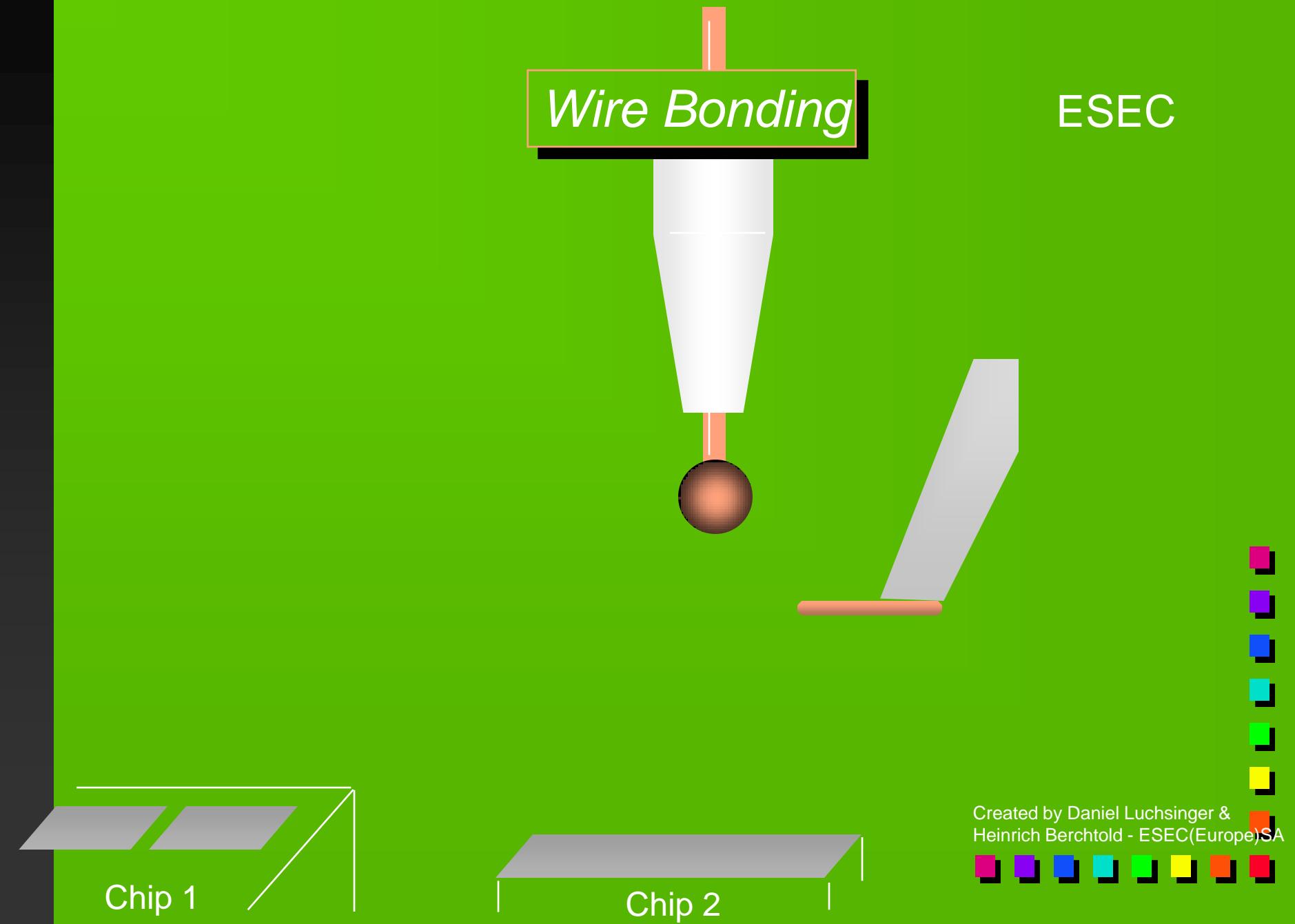


# *Wire Bonding*

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Chip 1

Chip 2

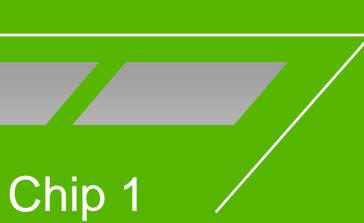
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Air Drag



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Ball Search Height

Chip 1

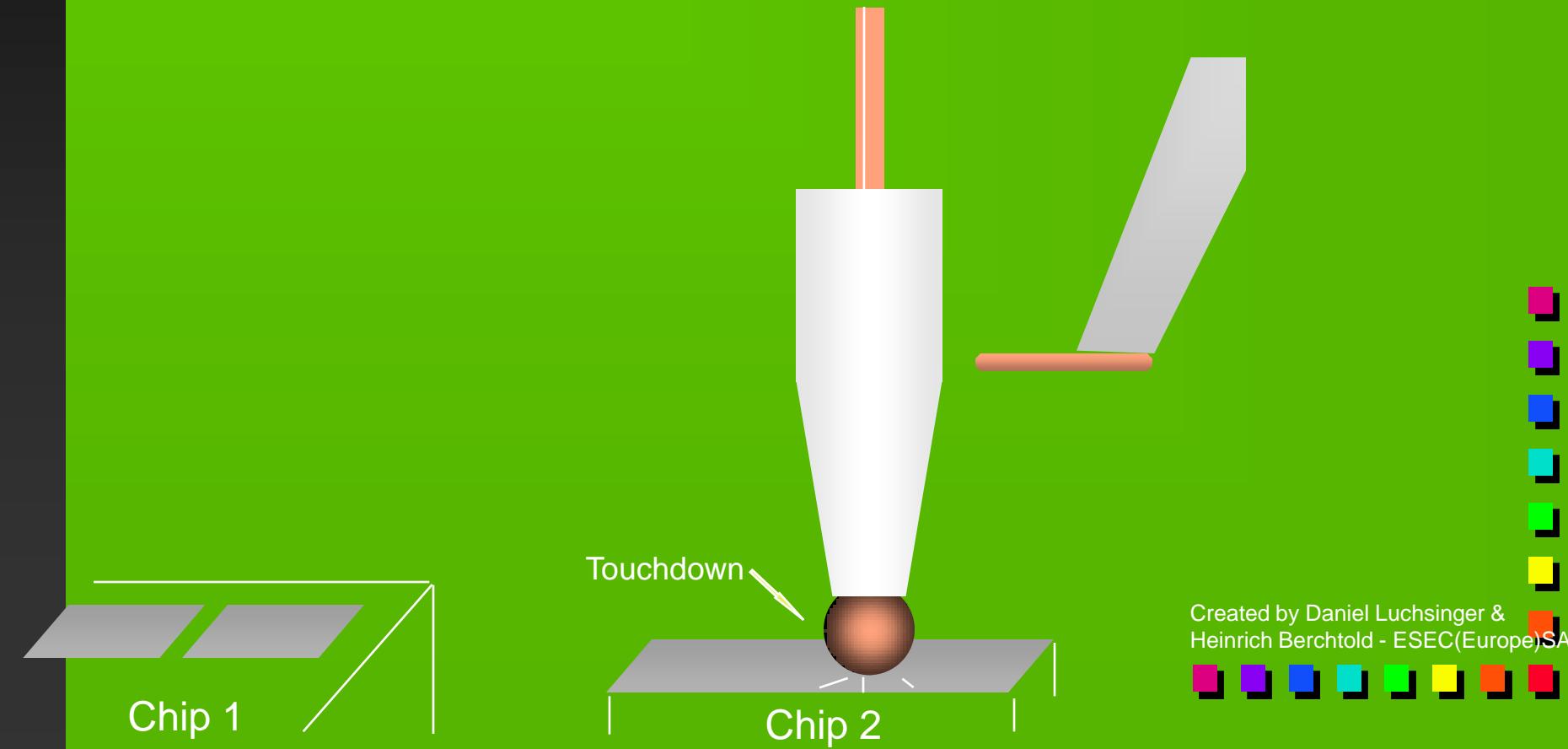
Chip 2

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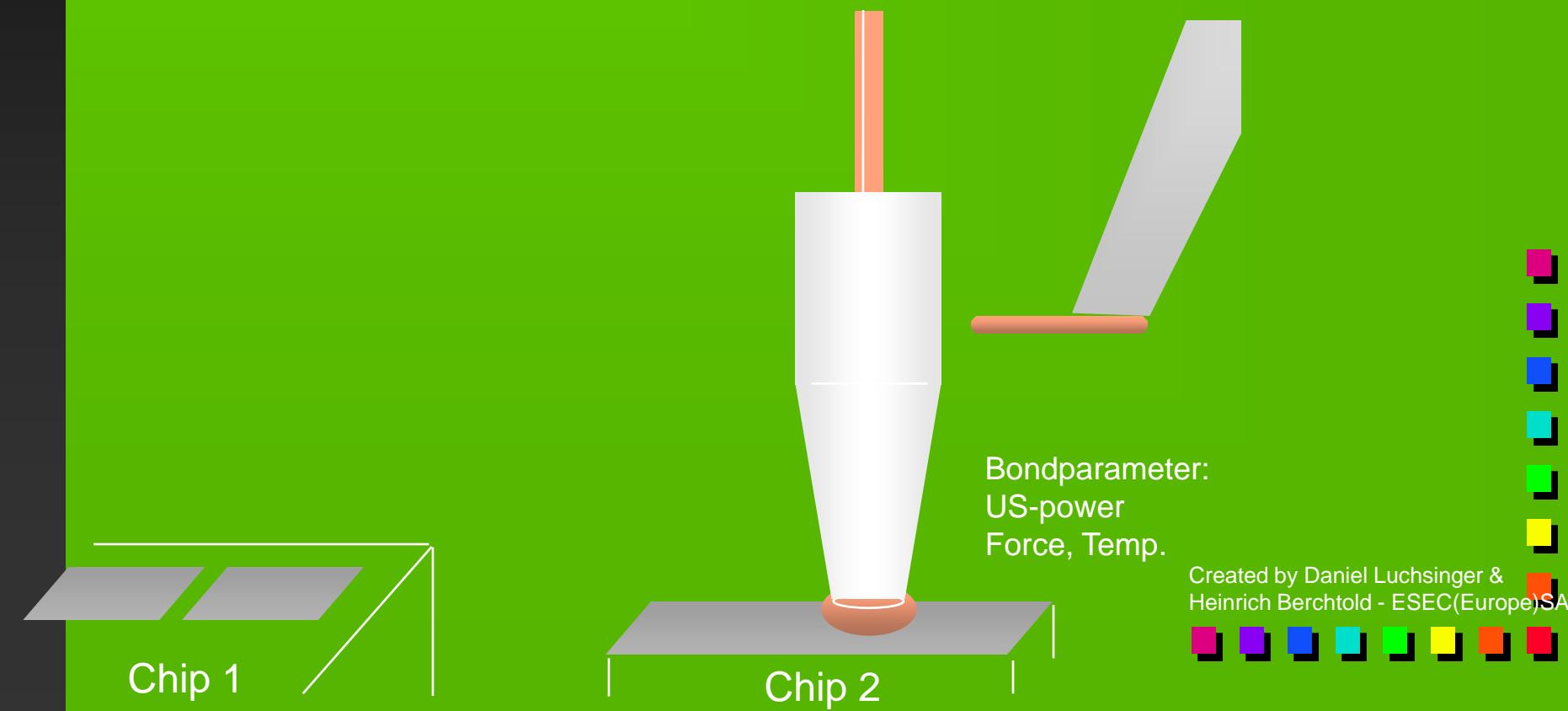


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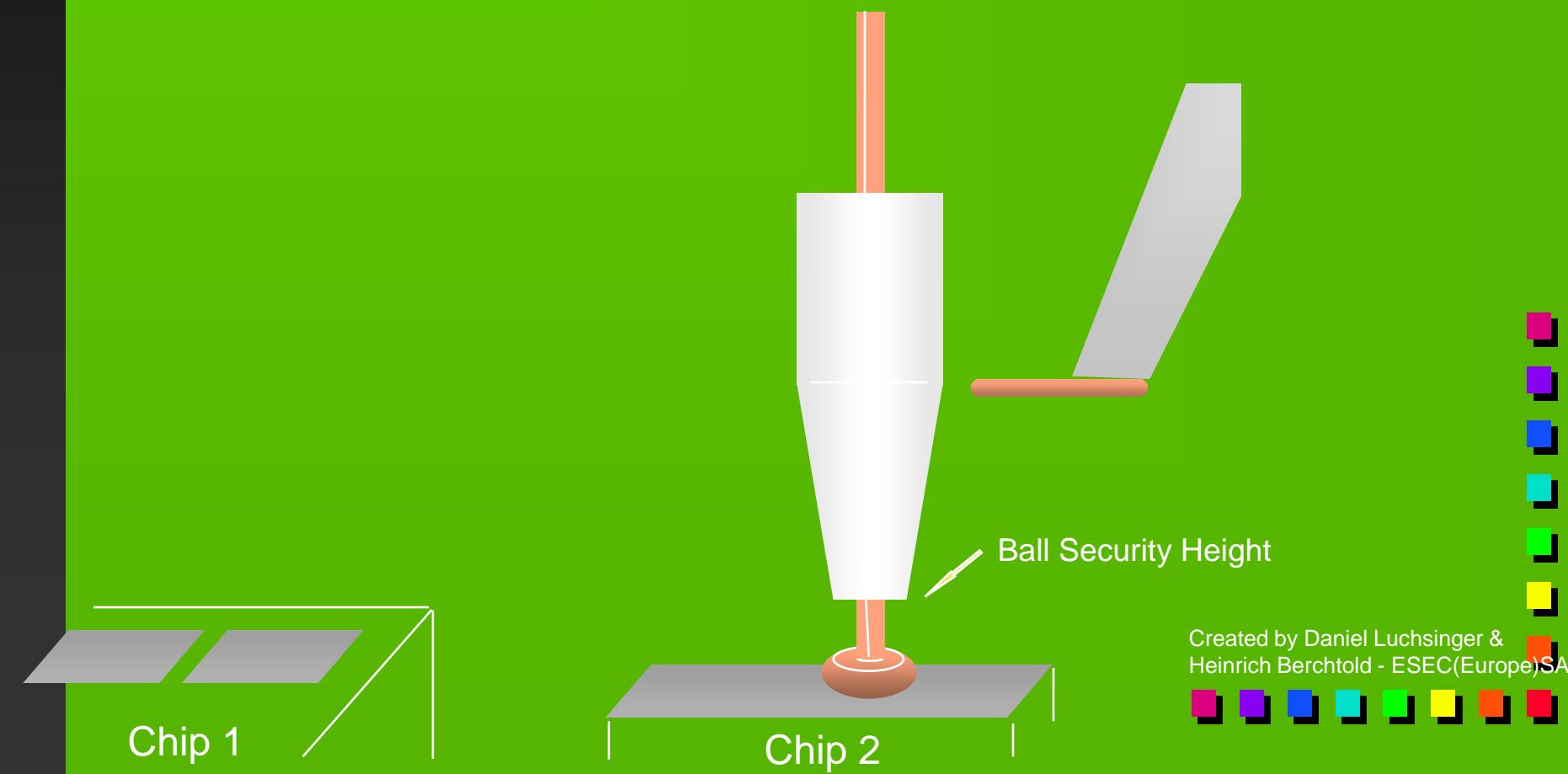
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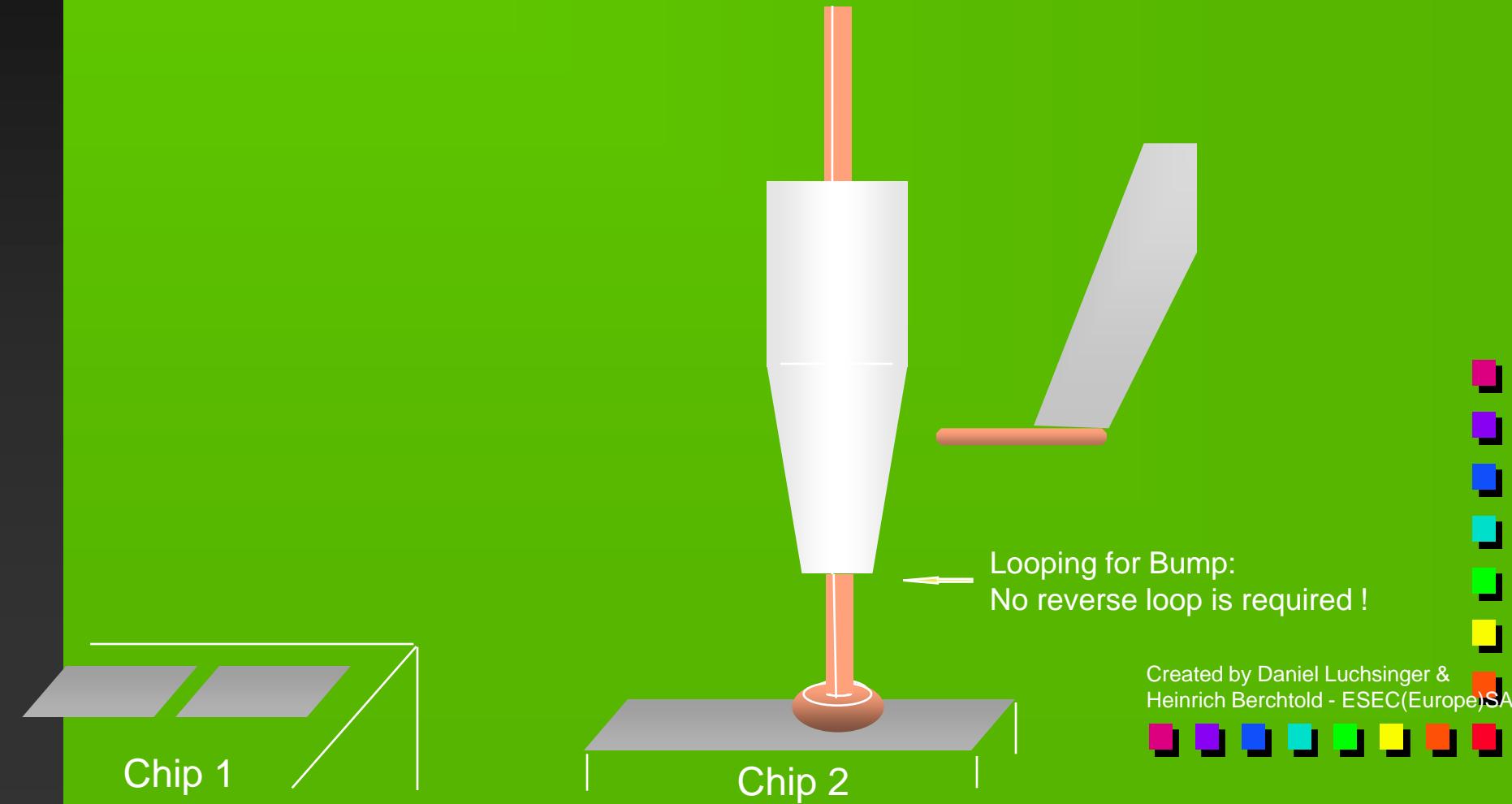
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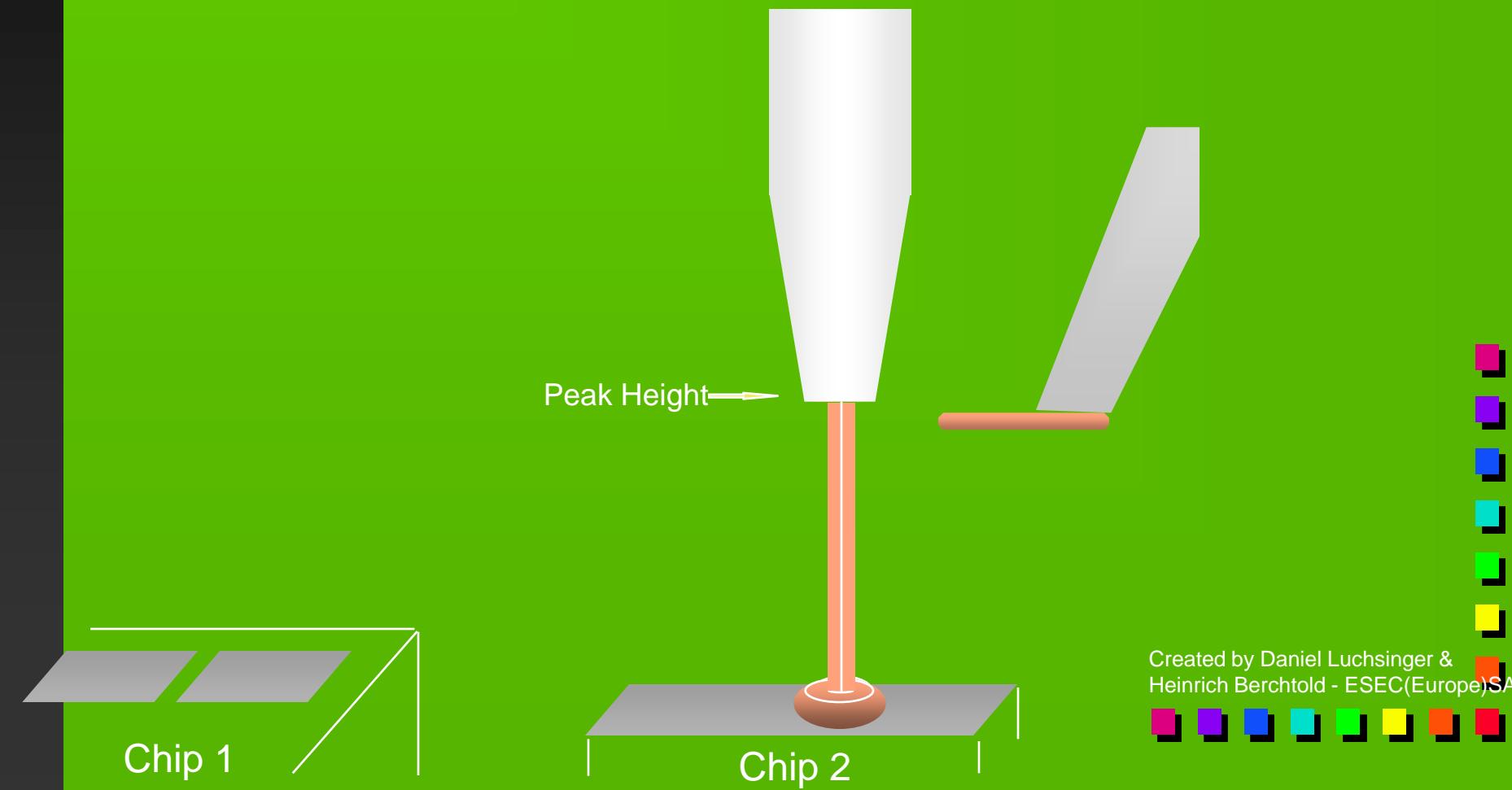
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# *Wire Bonding*

ESEC

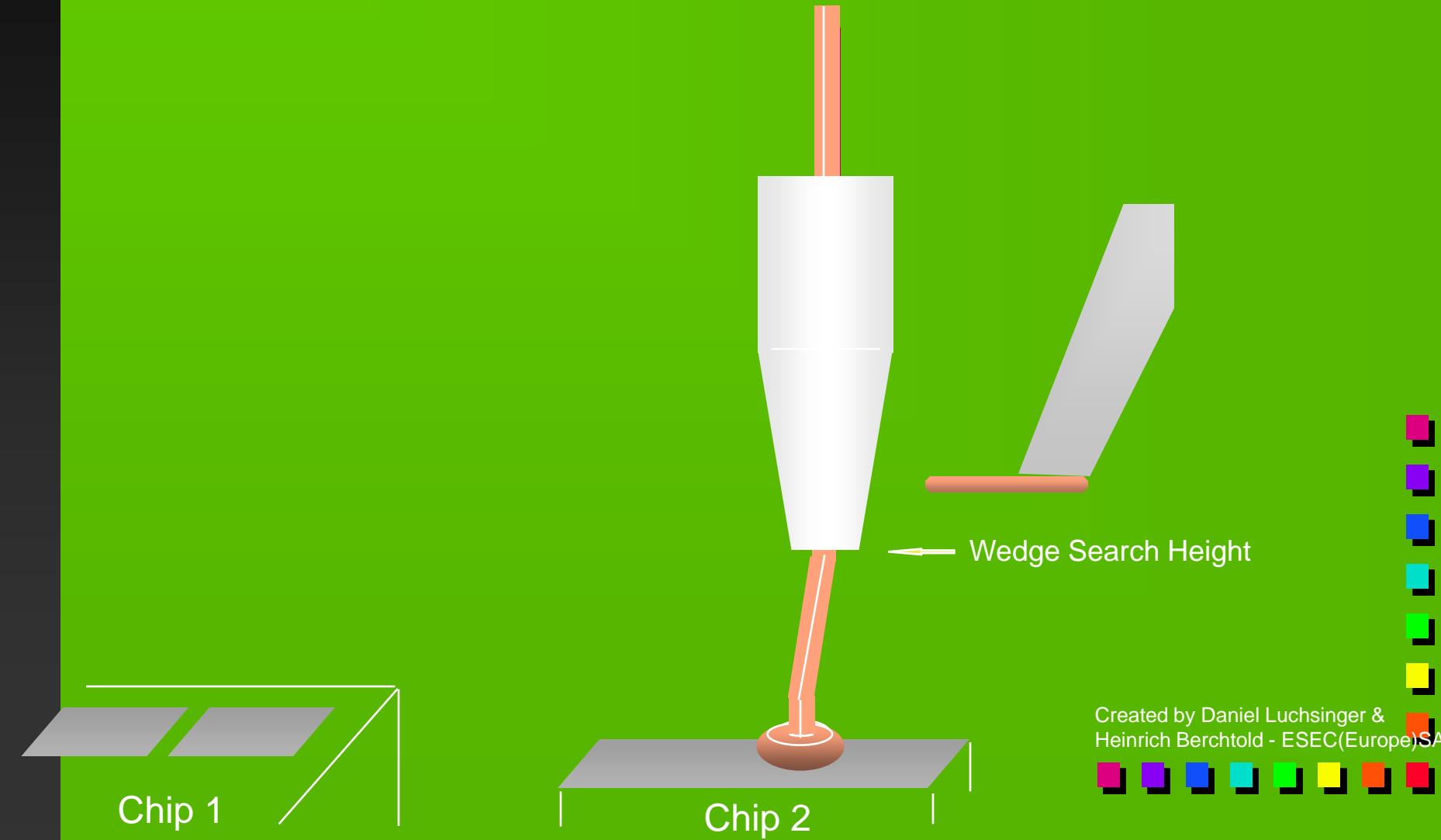


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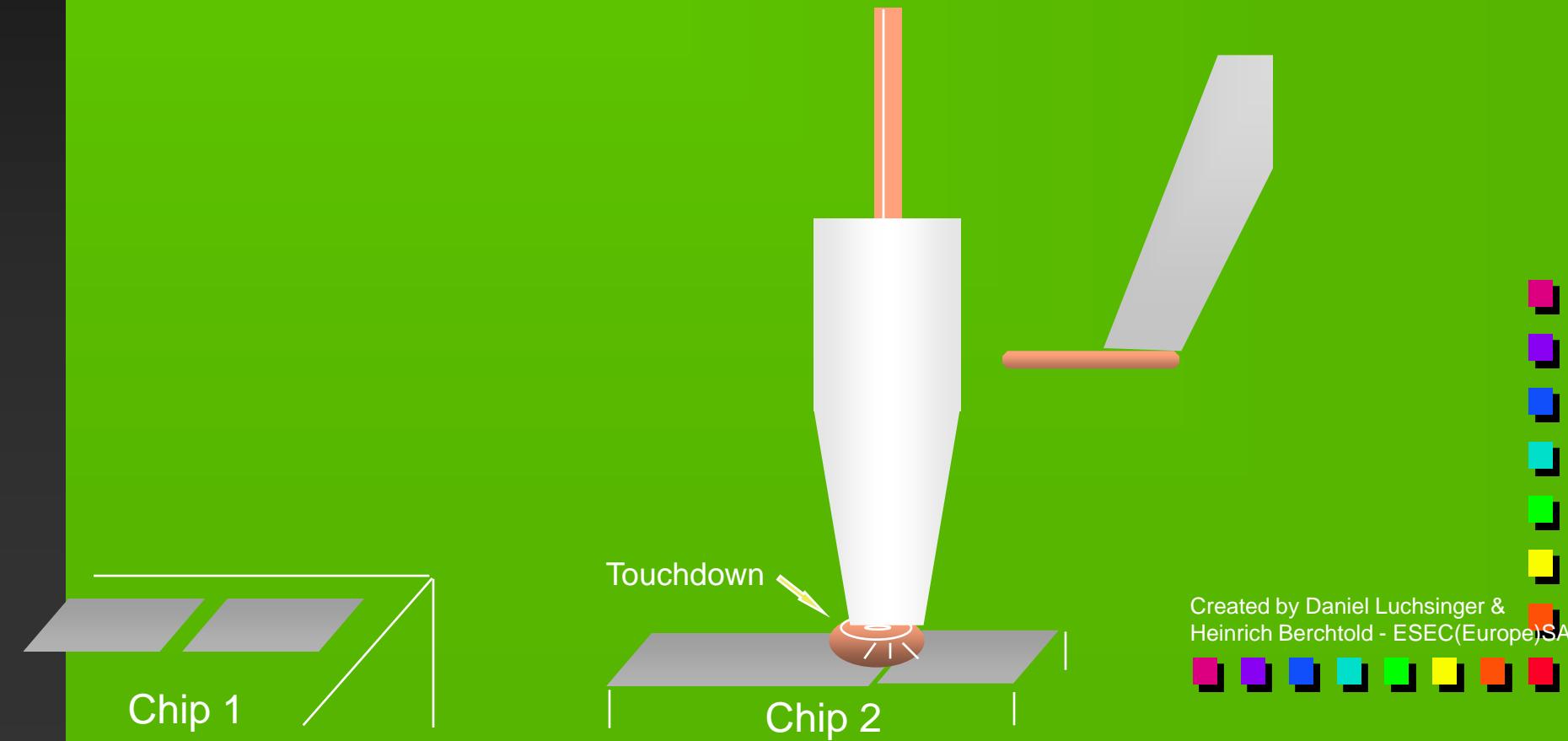
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# *Wire Bonding*

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Chip 1

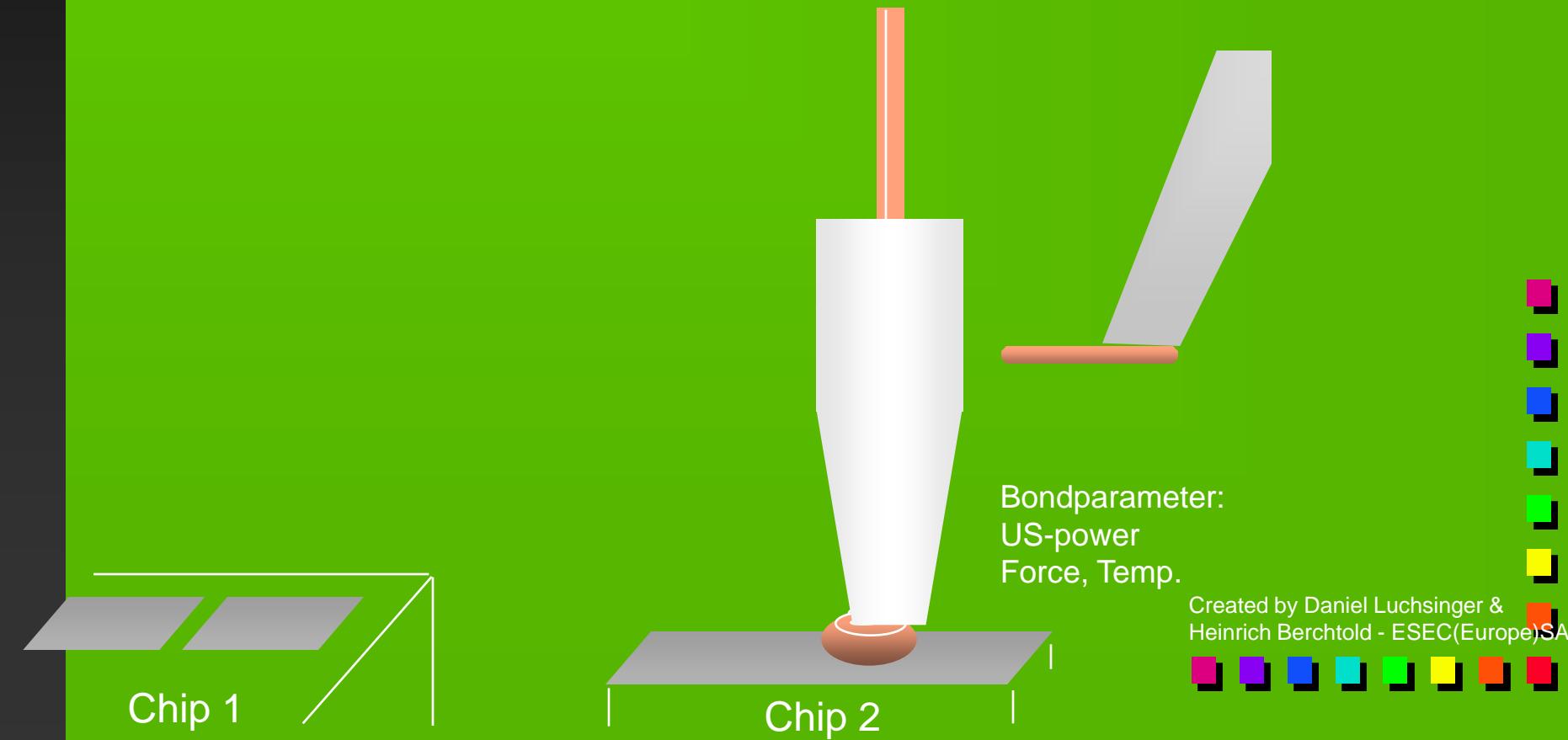
Chip 2

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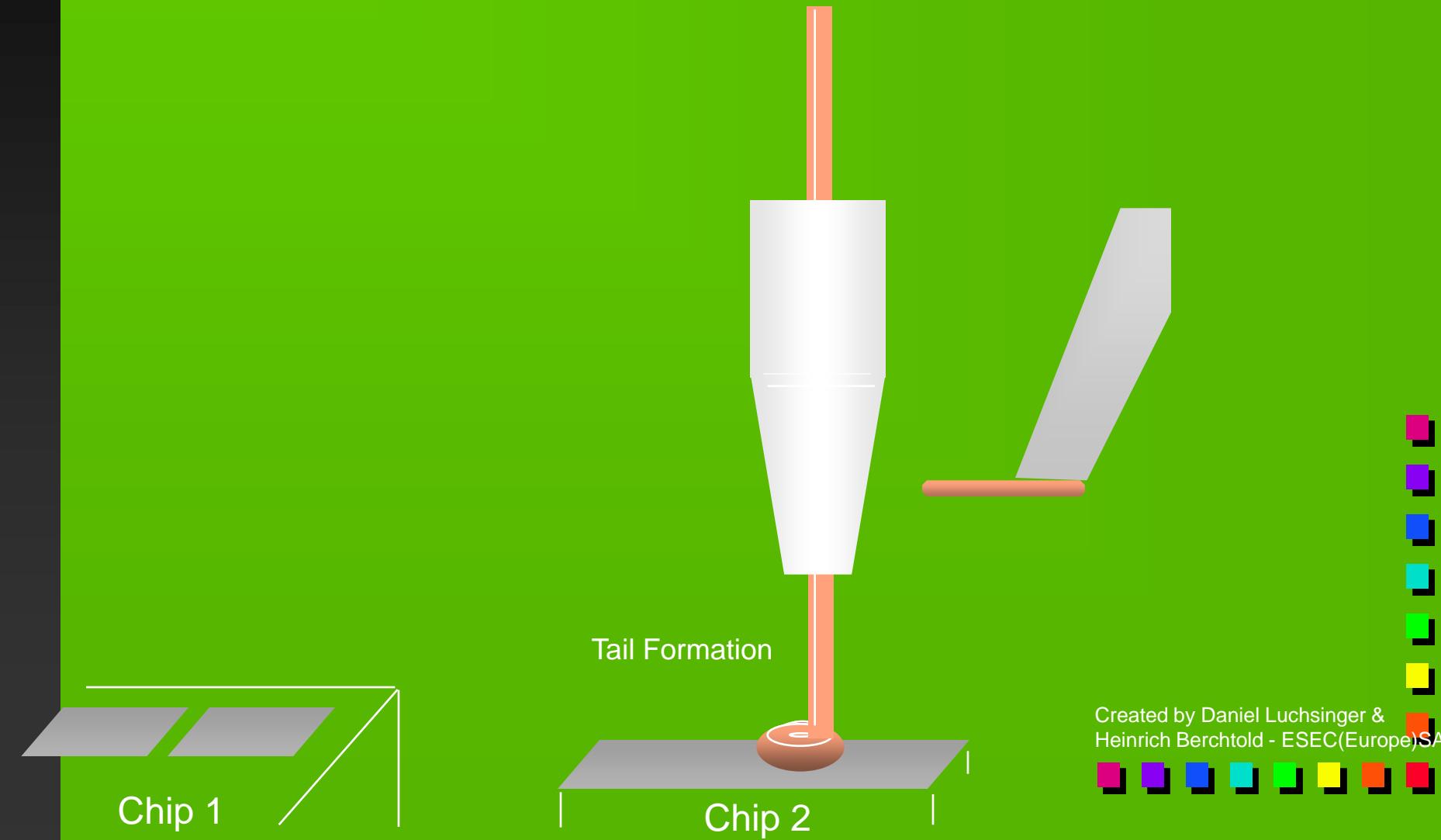
Chip 1

Chip 2

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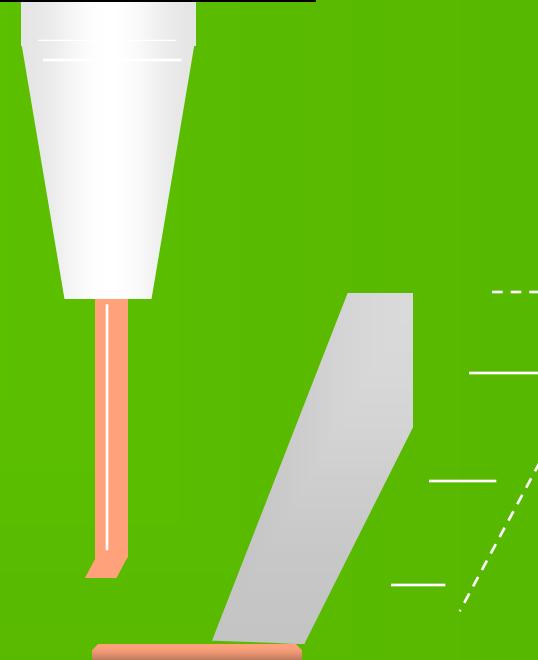


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EFO Blade Act

Chip 1

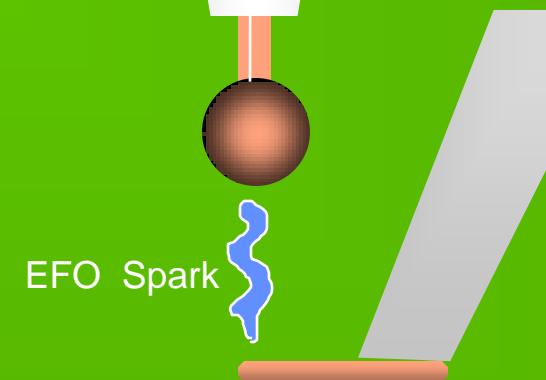
Chip 2

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Chip 1

Chip 2

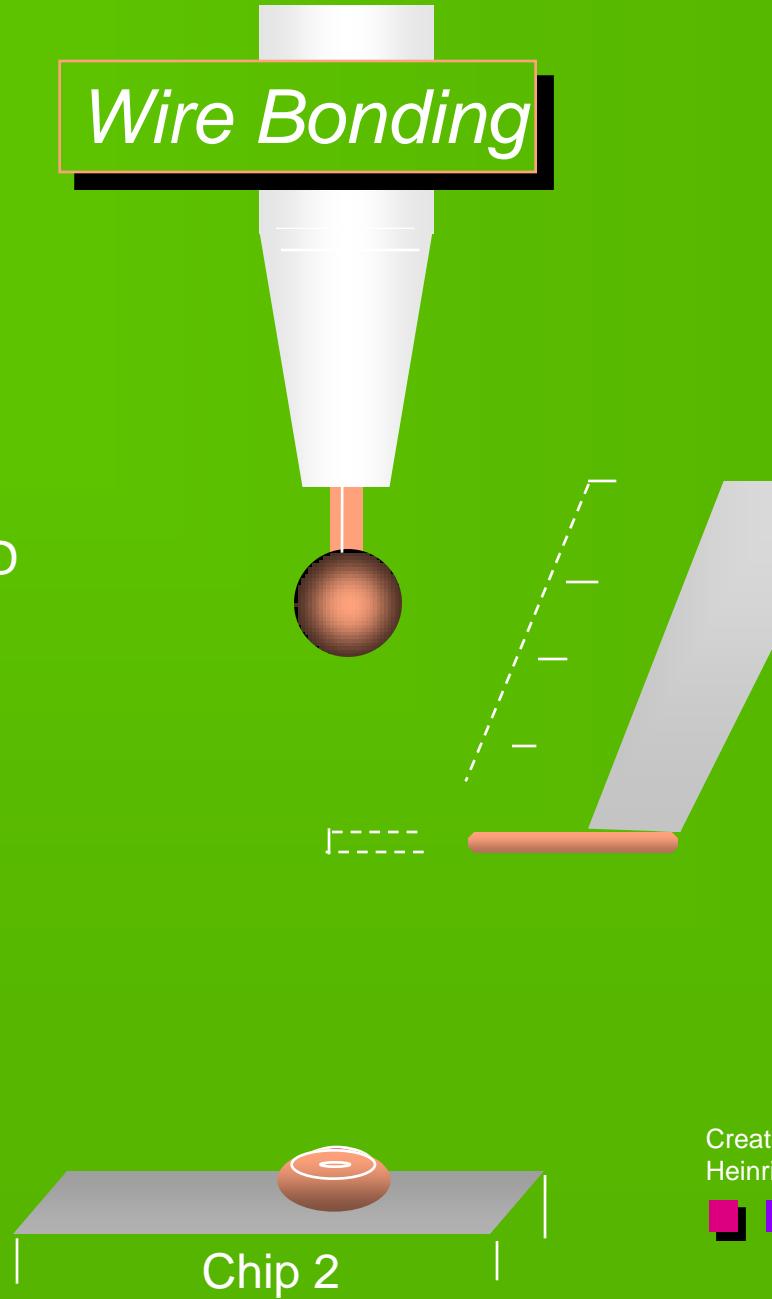
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# *Wire Bonding*

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BUMP  
COMPLETED



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Chip 2

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# Wire Bonding

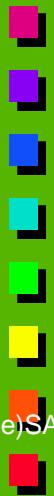
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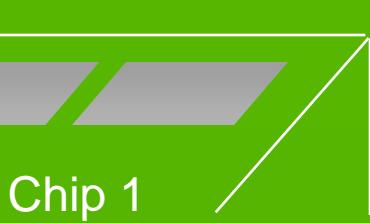


Chip 1

Chip 2

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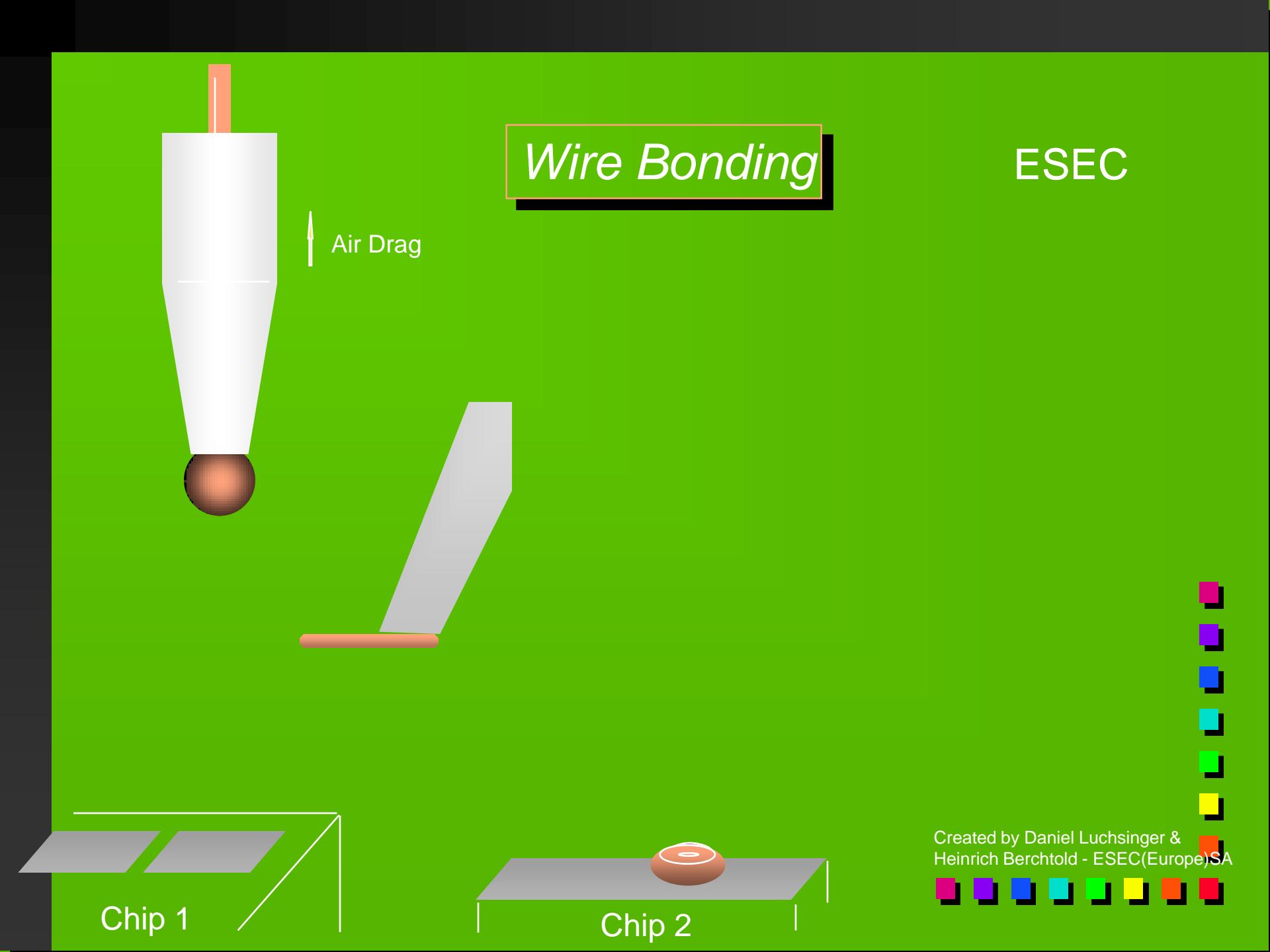


# Wire Bonding

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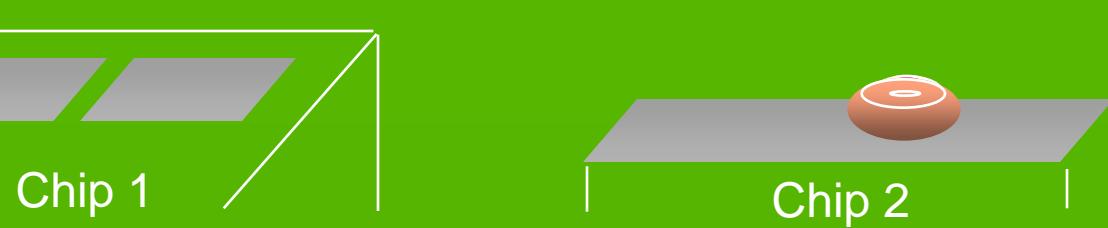
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## Wire Bonding



Chip 1

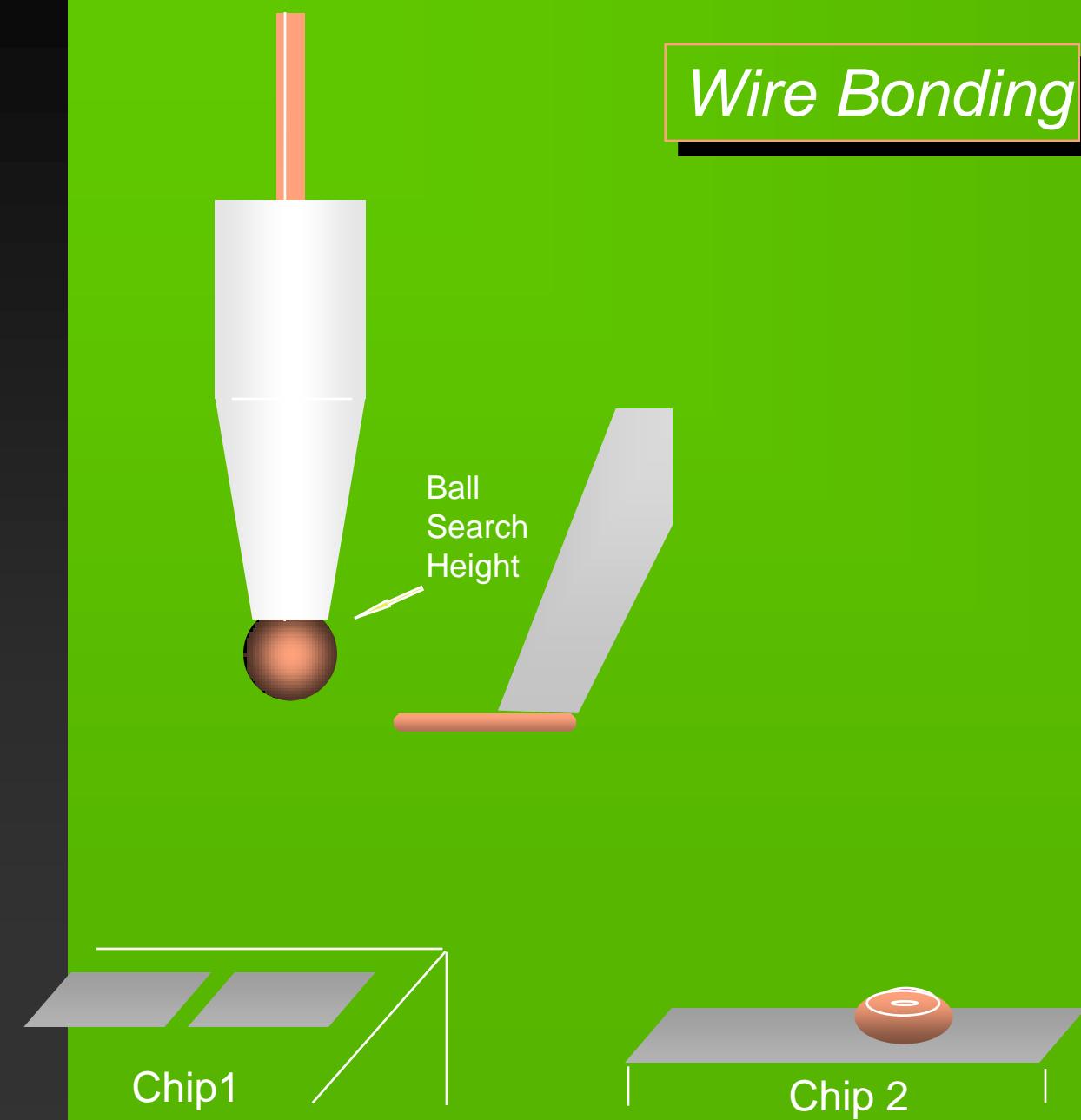
Chip 2

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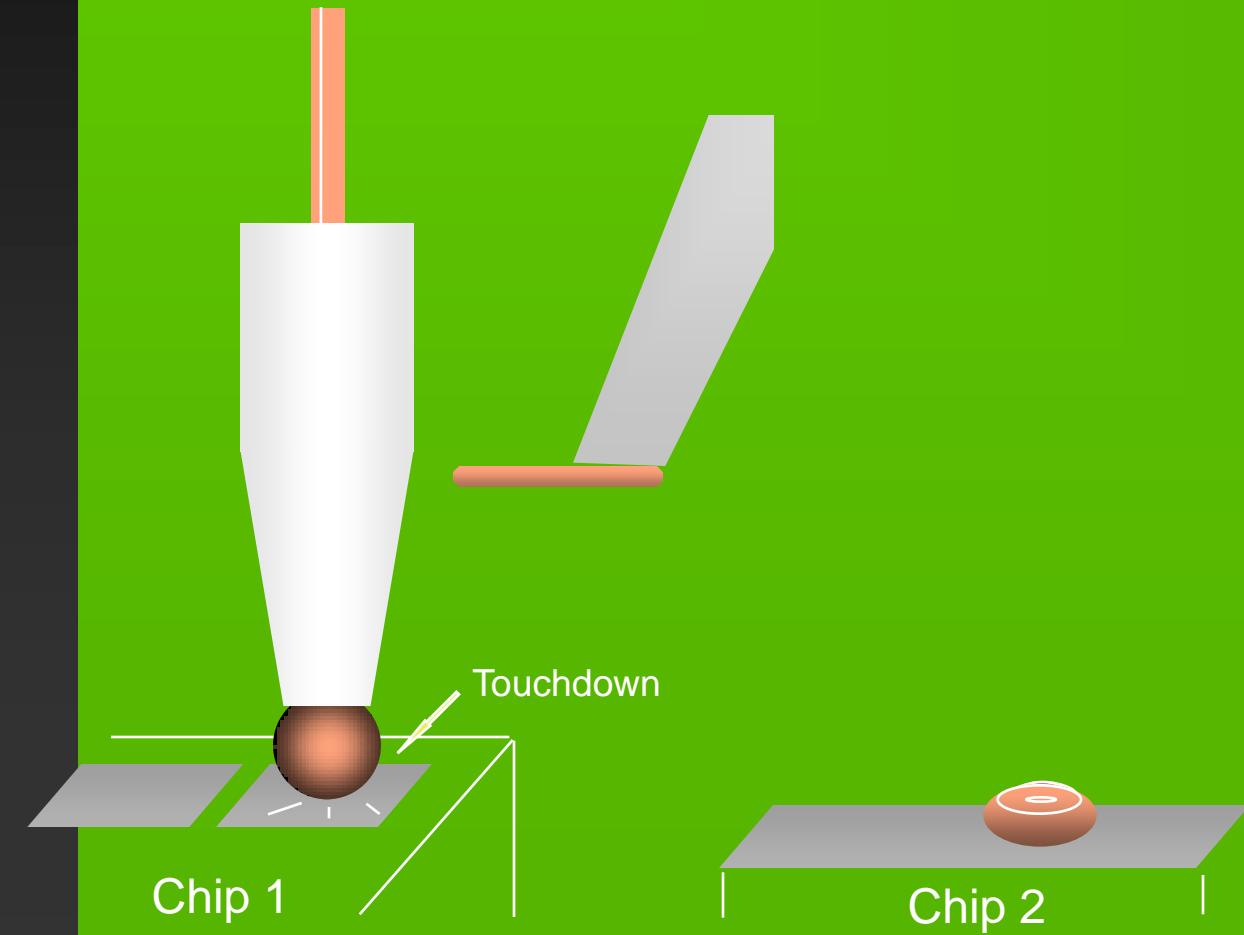


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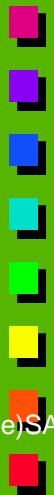
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Chip 1

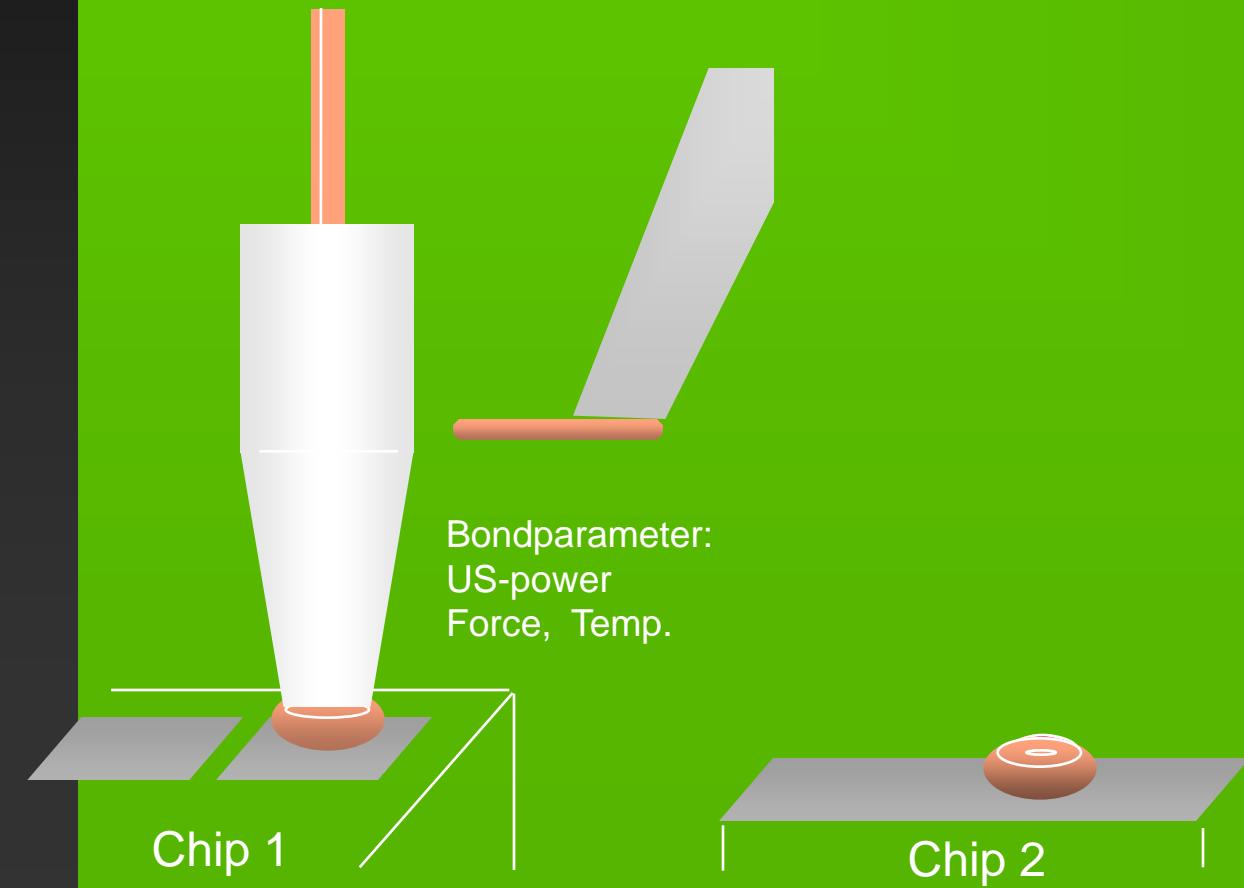
Chip 2

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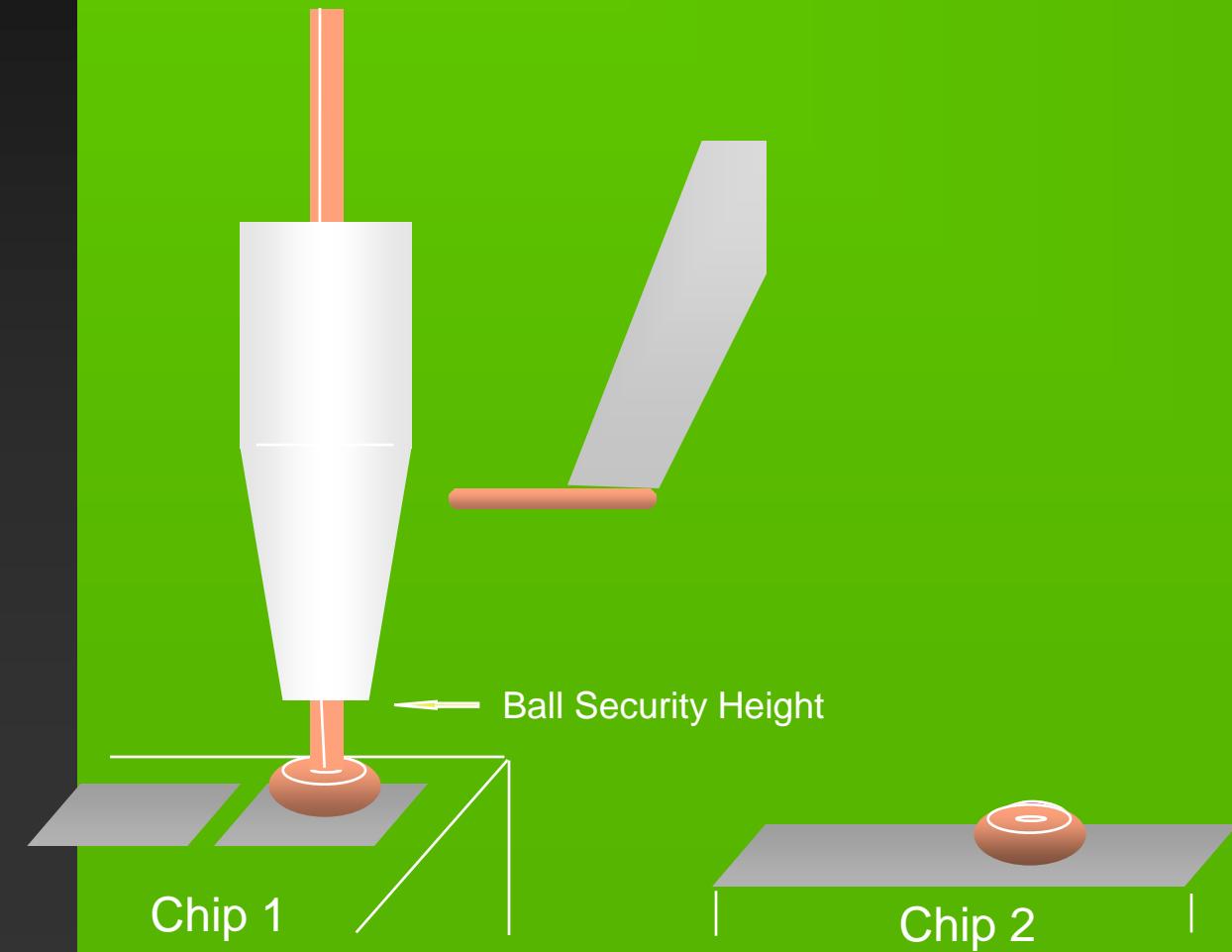


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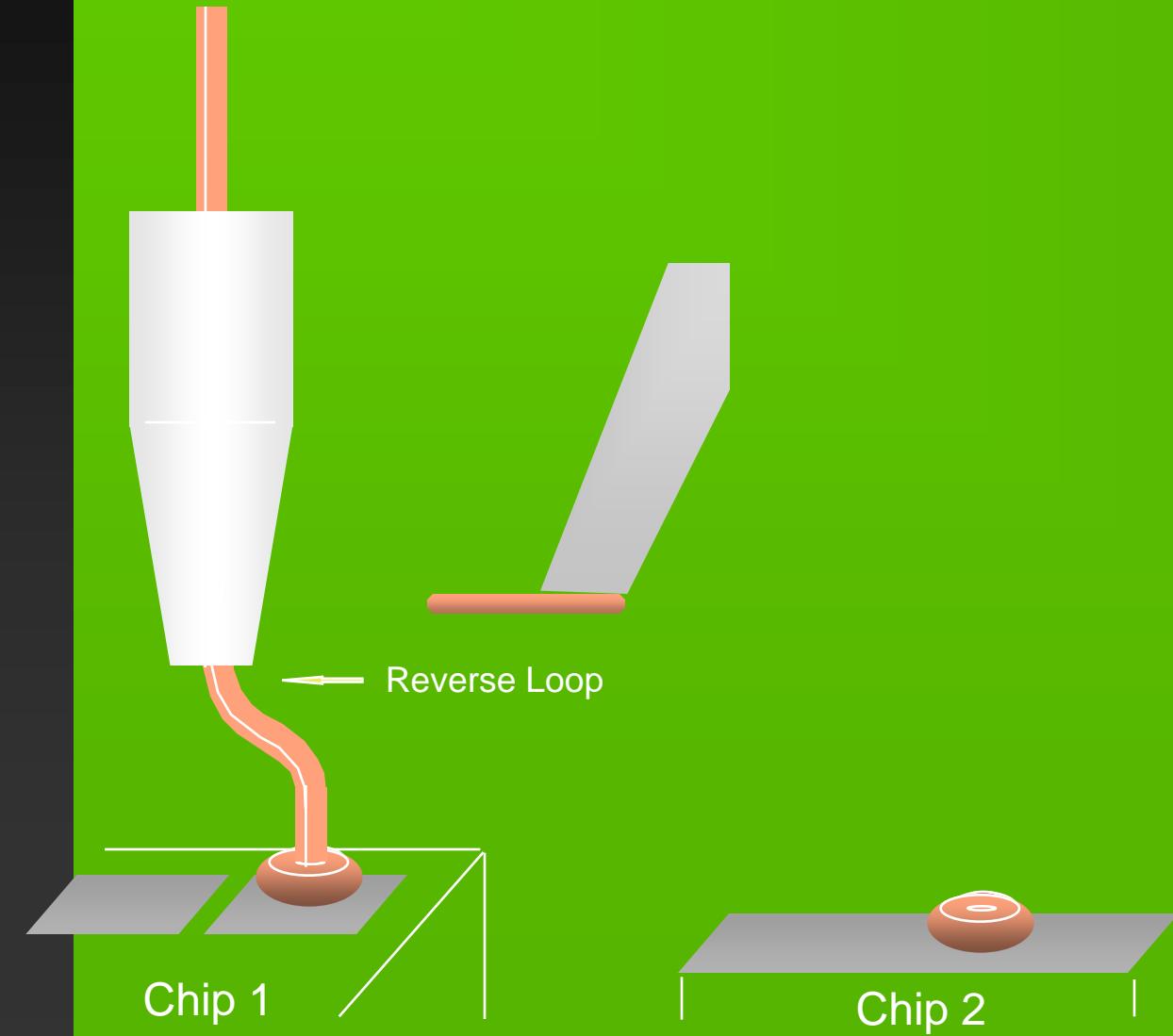


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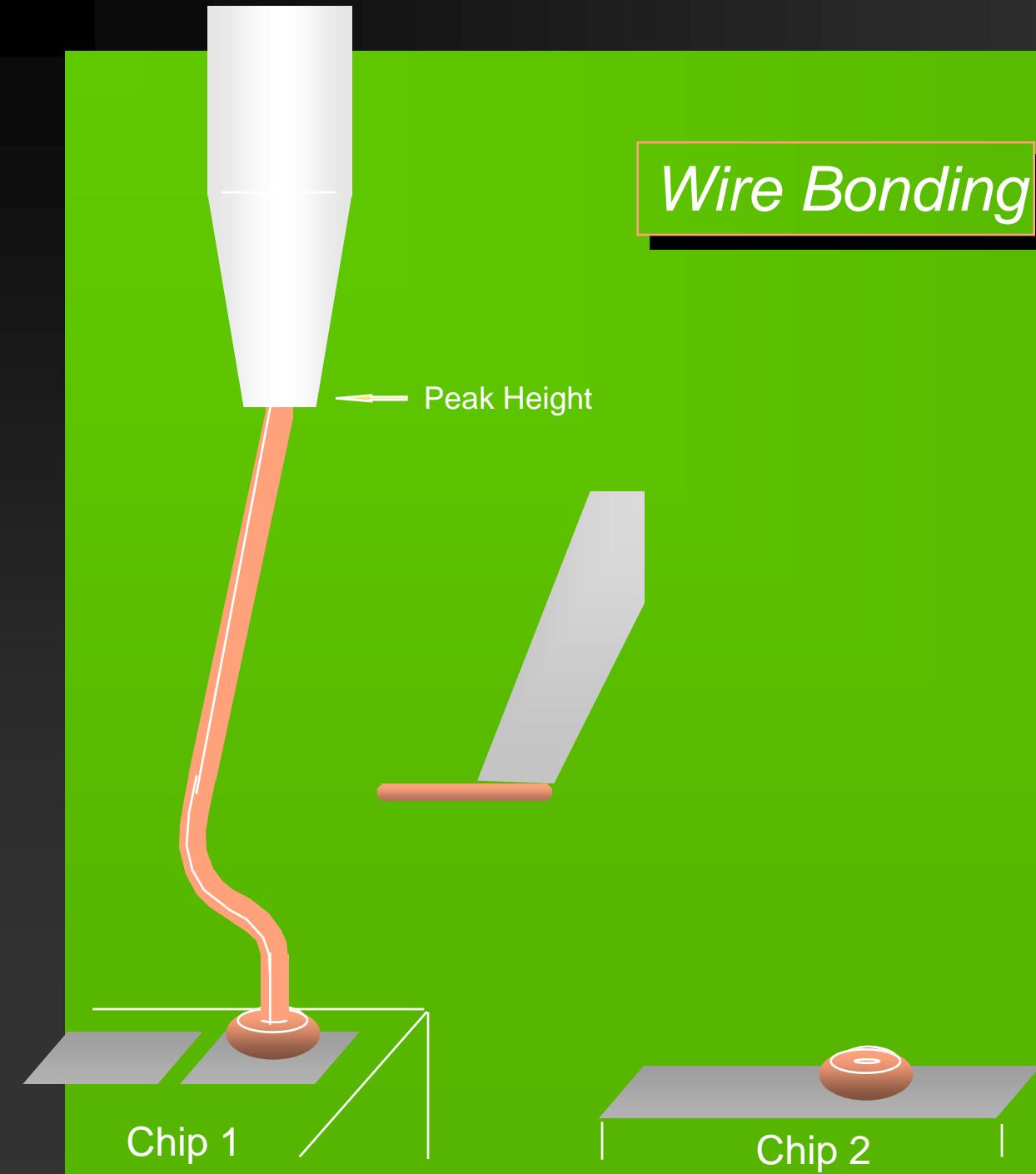


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Chip 1

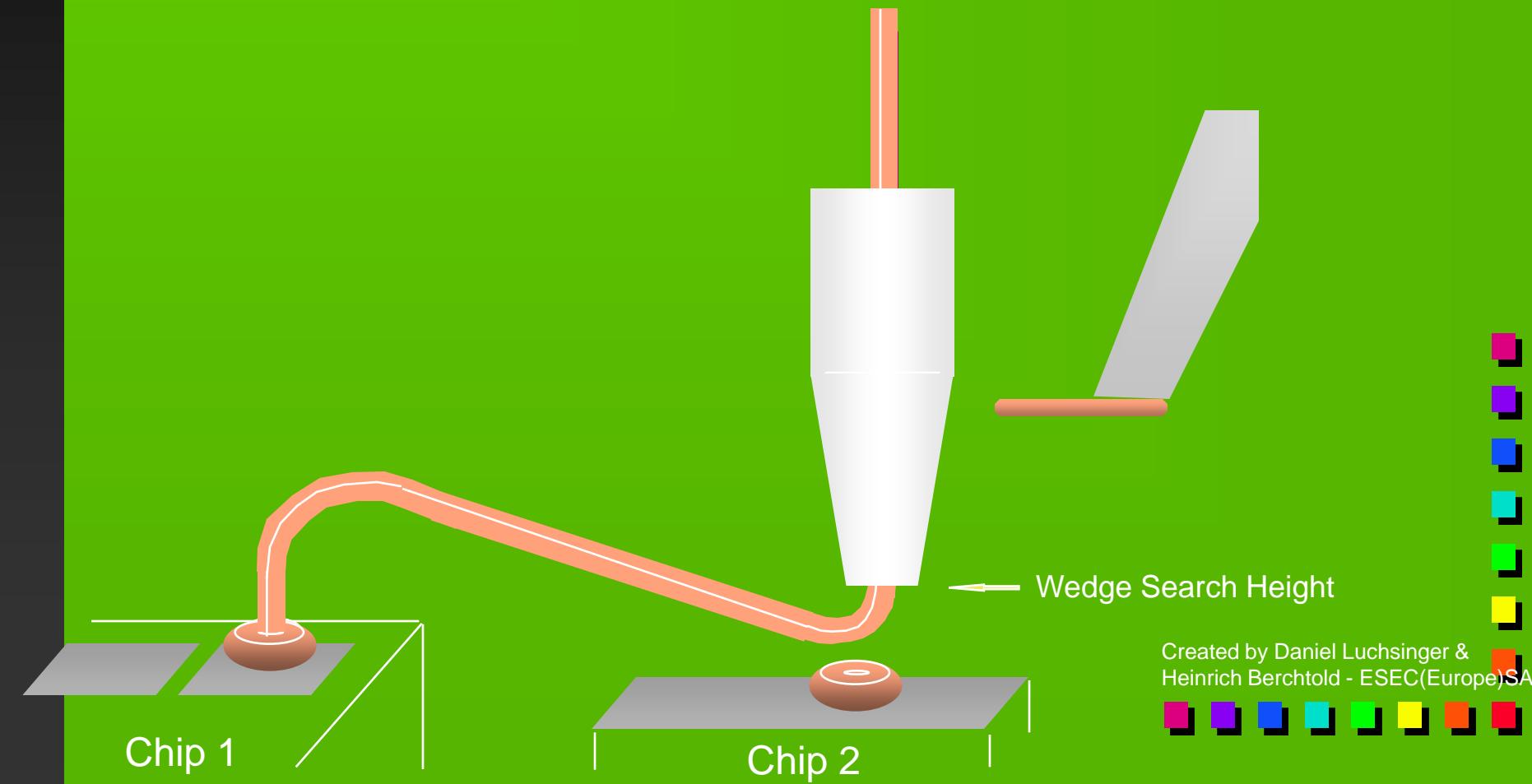
Chip 2

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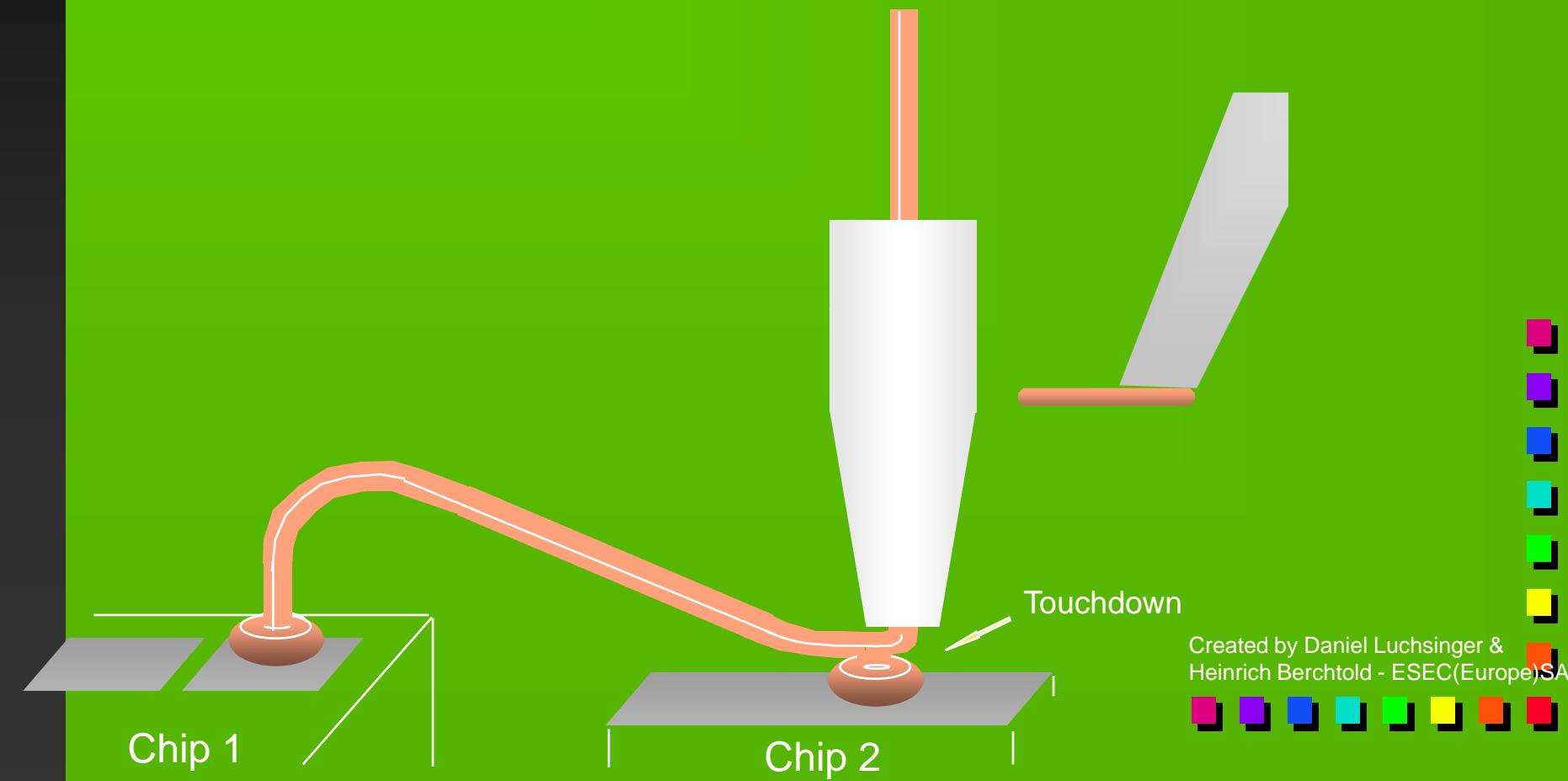
# *Wire Bonding*

ESEC



# *Wire Bonding*

ESEC

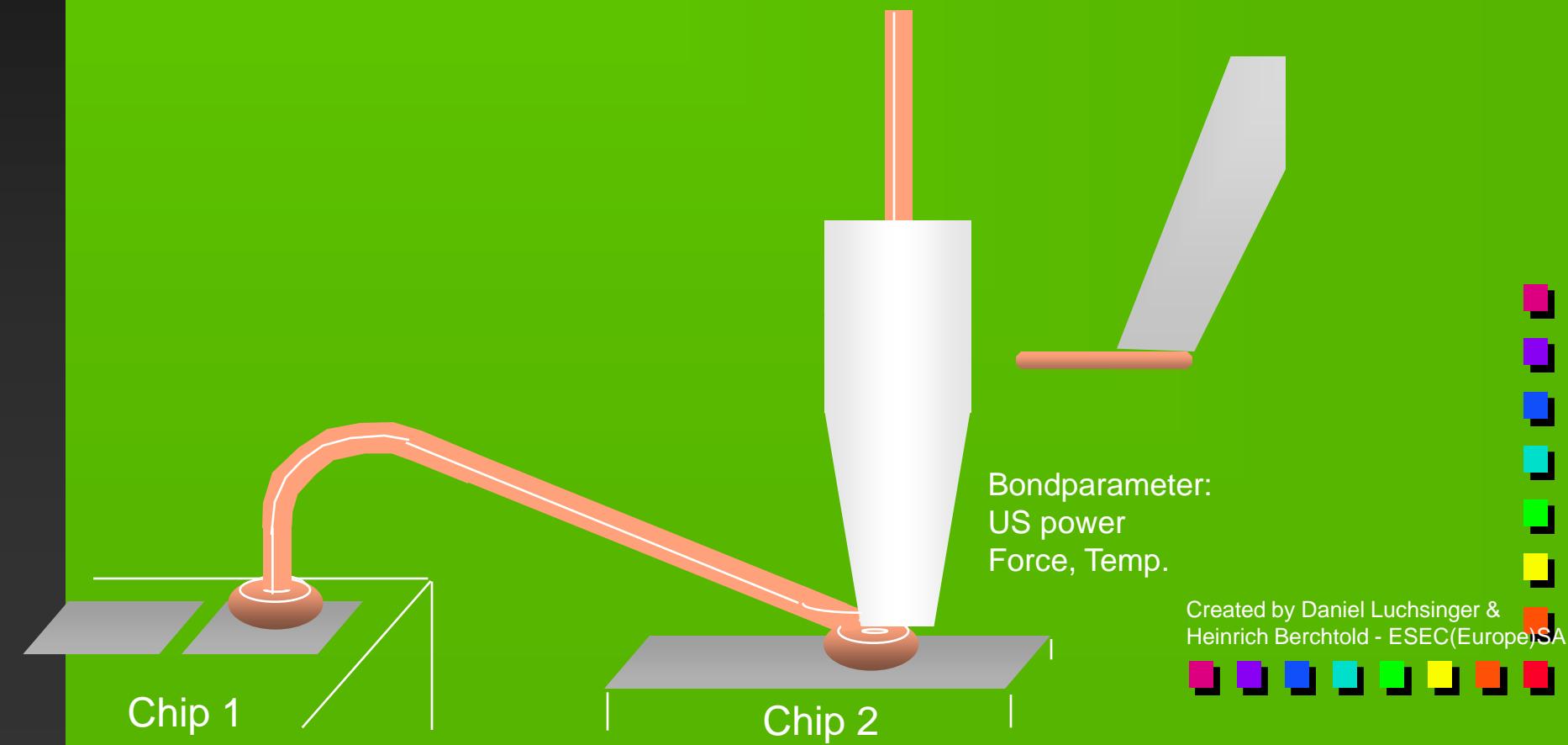


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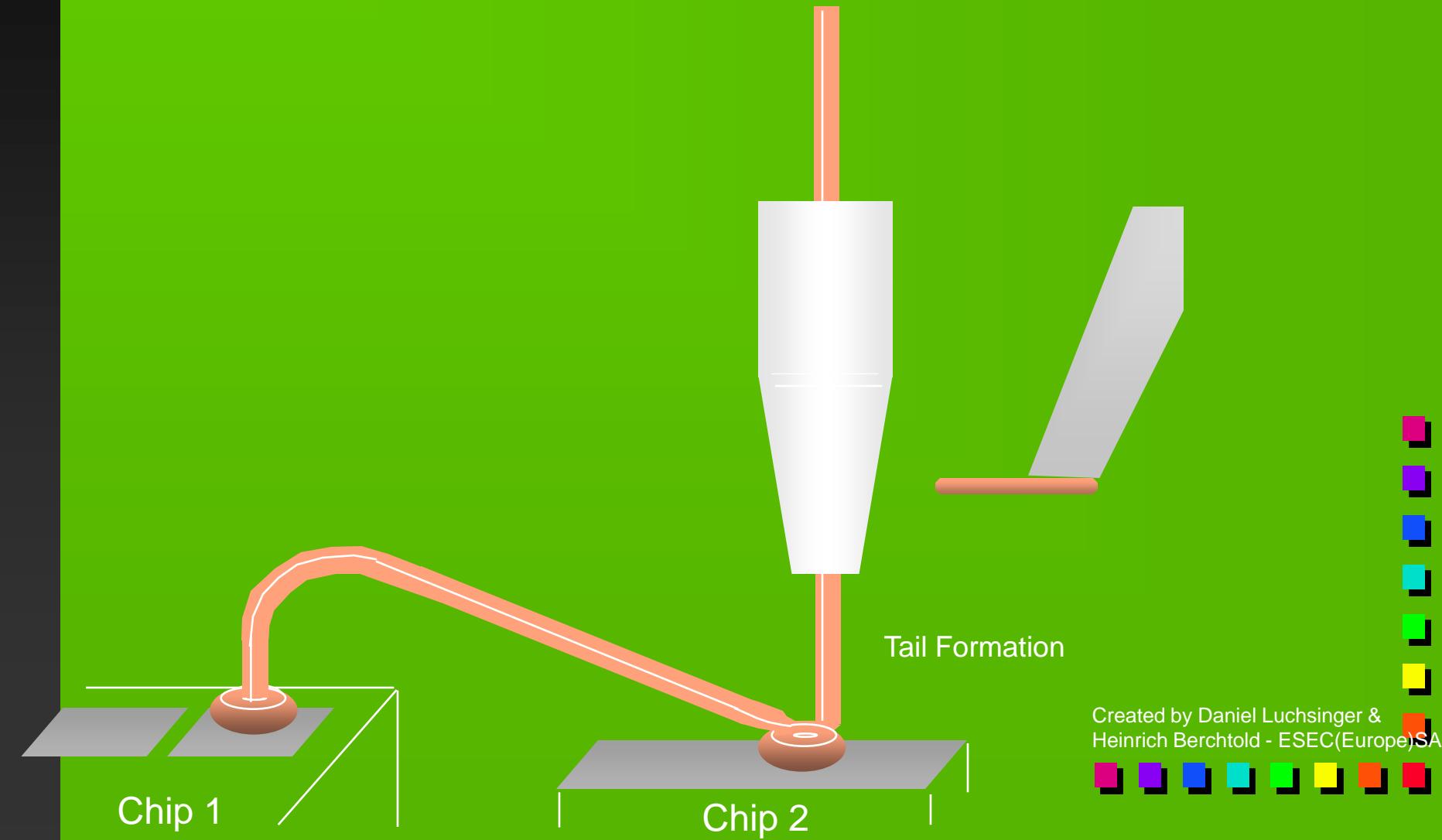
# *Wire Bonding*

ESEC



# *Wire Bonding*

ESEC

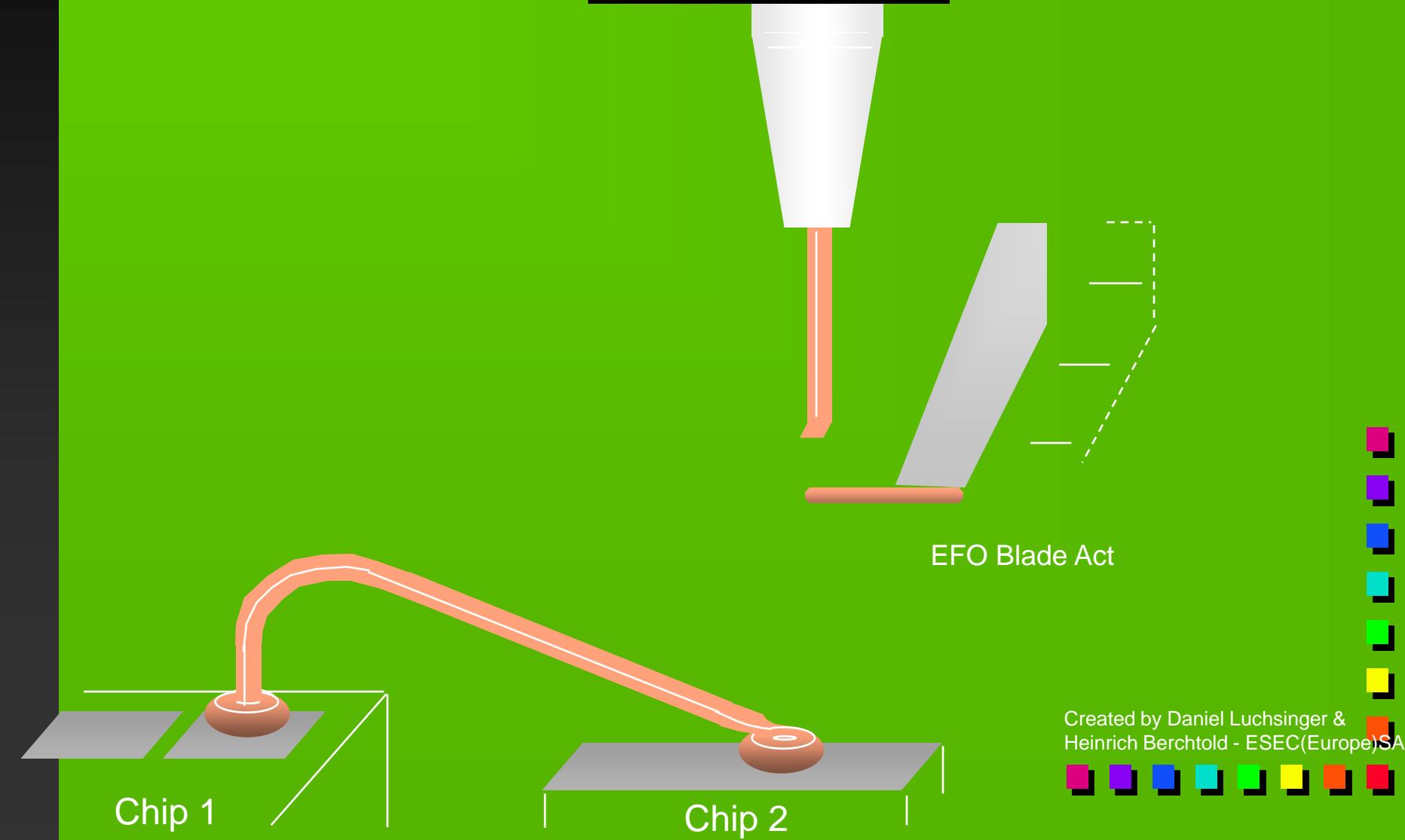


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Chip 1

Chip 2

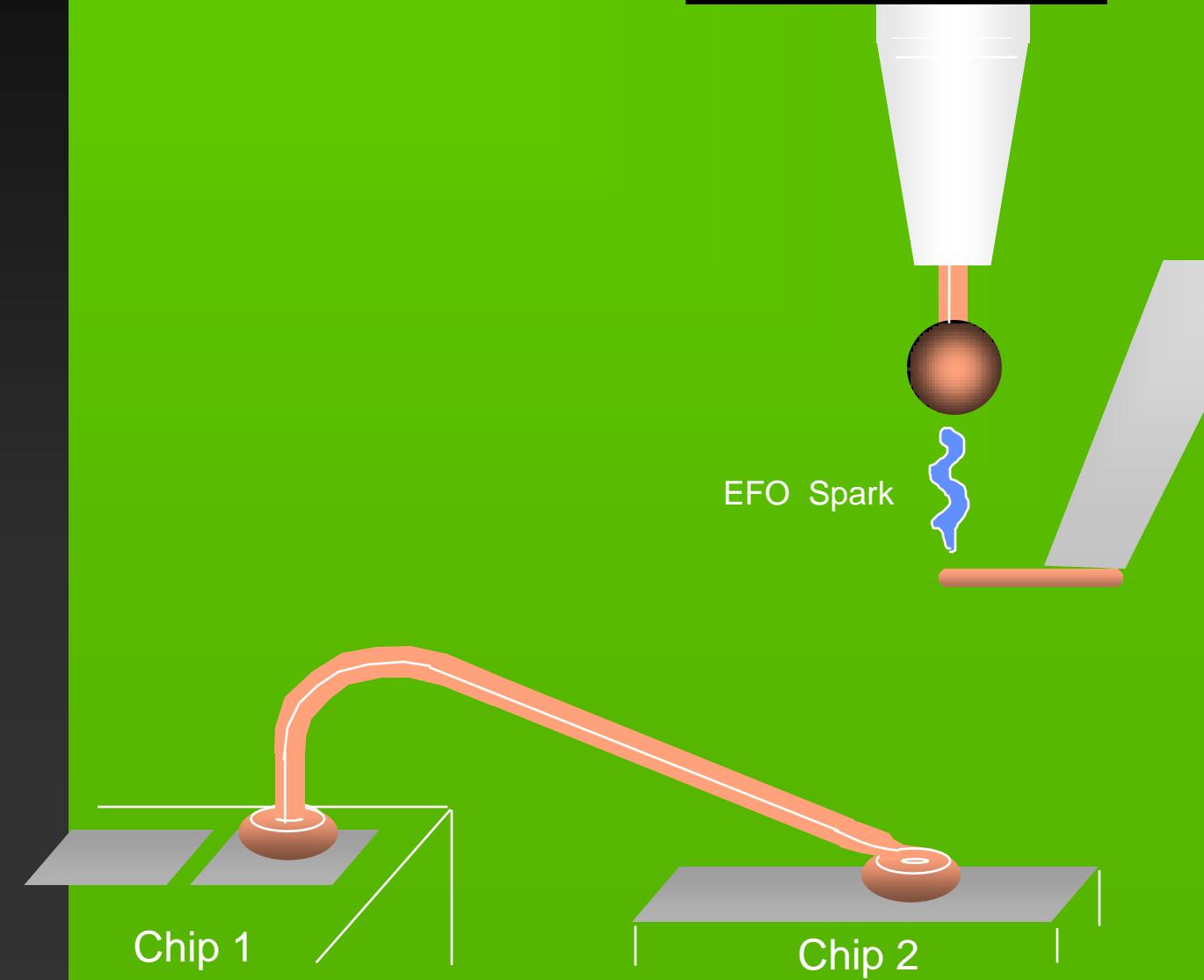
EFO Blade Act

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Chip 1

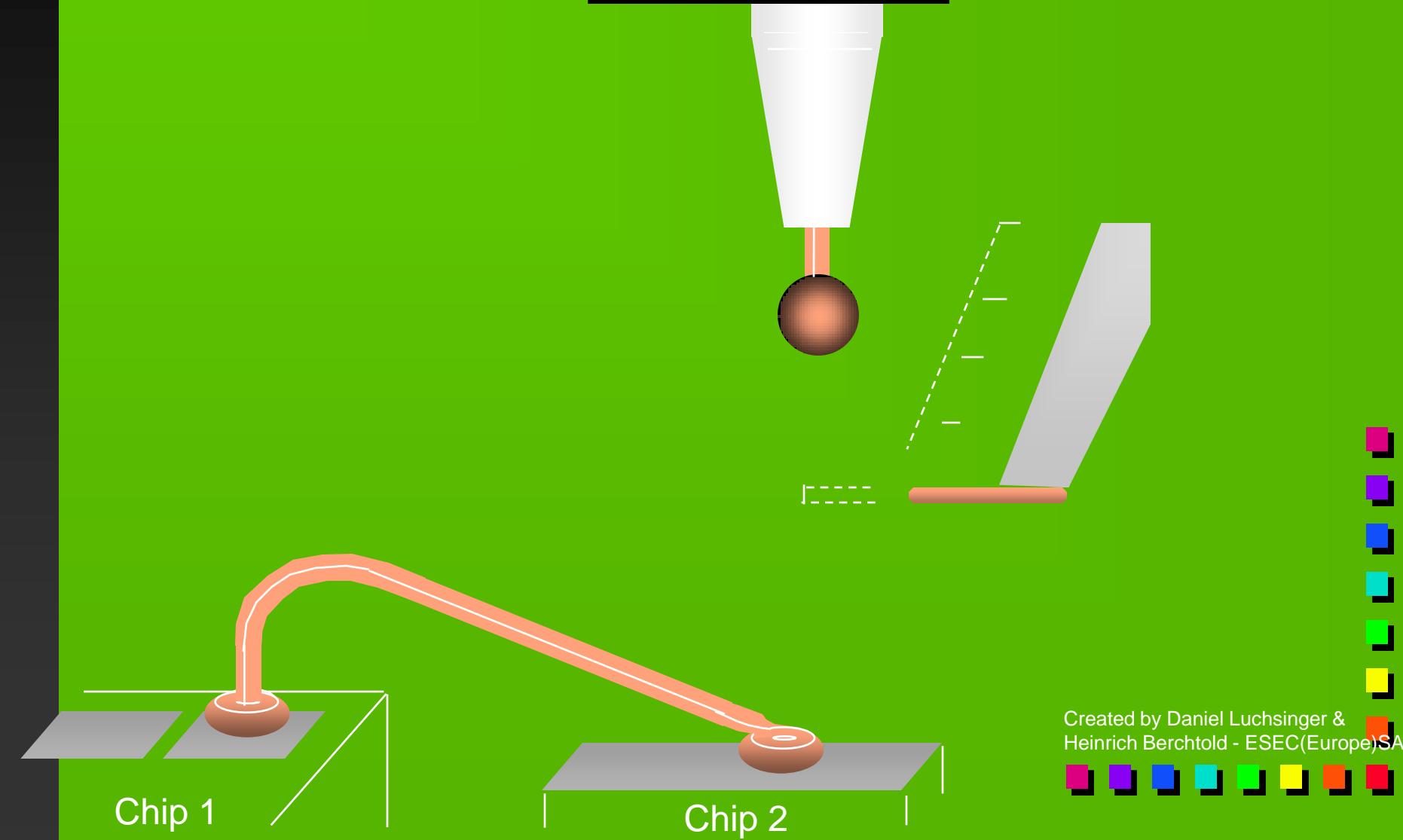
Chip 2

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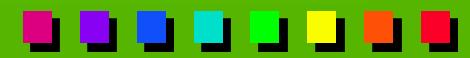


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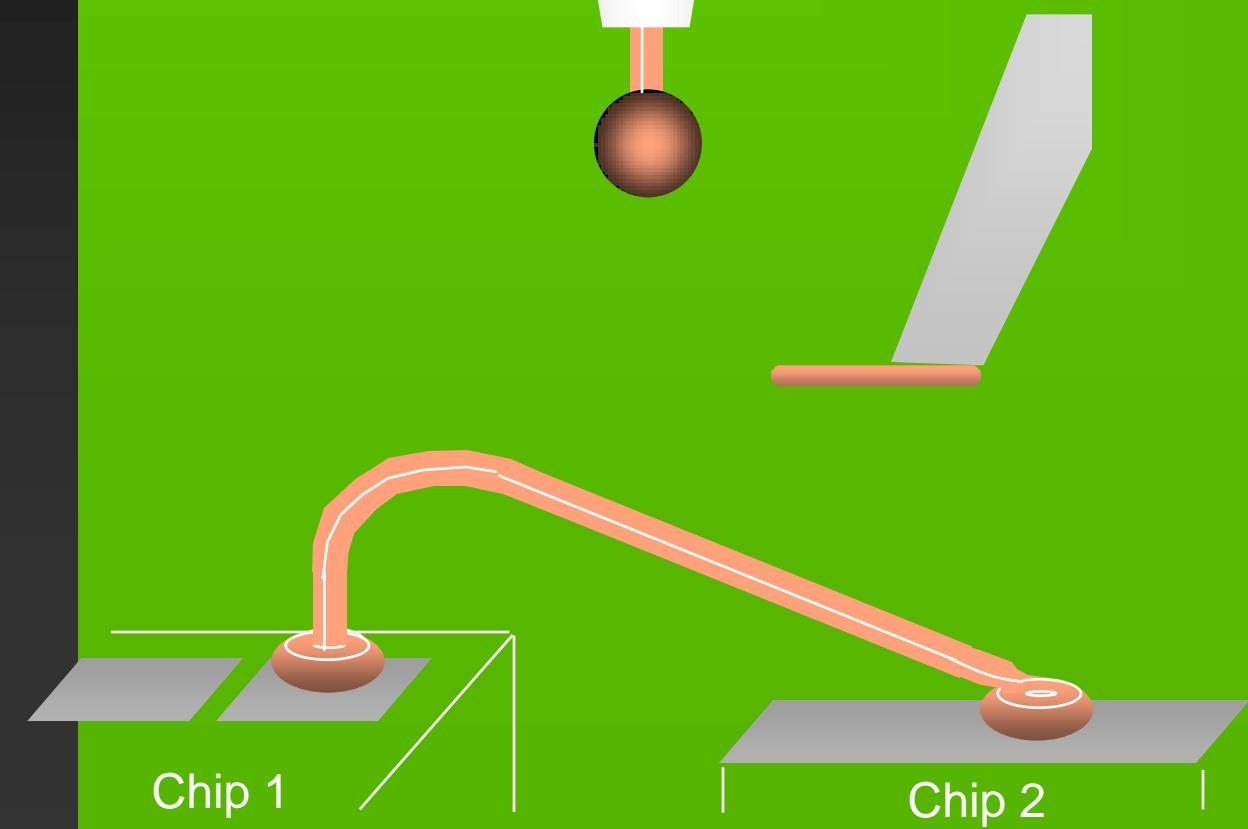


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